

ABSTRACT

A copper alloy for an electronic and electric device is provided. The copper alloy includes: Mg in a range of 0.15 mass% or more and less than 0.35 mass%; and a Cu balance including inevitable impurities, wherein the electrical conductivity of the copper alloy is more than 75%IACS, and a yield ratio YS/TS, which is calculated from strength TS in a tensile test performed in a direction parallel to a rolling direction and 0.2% yield strength YS, is more than 88%. The copper alloy may further include P in a range of 0.0005 mass% or more and less than 0.01 mass%.